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Vishay Sfernice

SMD Wraparound Ultra Low Value Thin Film Resistors



www.vishay.com

LINKS TO ADDITIONAL RESOURCES



With extremely low resistance and high power capabilities, these ultra low value resistors are available with solderable or weldable terminations.

FEATURES

- NiCr + Ta₂O₅ resistive layer
- · Pre-soldered or gold terminations
- No inductance for high frequency applications
- · Alumina substrates for high power handling capability
- Resistance range: 0.1 Ω to 9.99 Ω
- TCR down to 50 ppm/°C
- Power rating: up to 2 W at +70 °C
- Withstand AEC-Q200 humidity test
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

STANDAR	STANDARD ELECTRICAL SPECIFICATIONS						
MODEL	SIZE	$\begin{array}{c} \textbf{RESISTANCE RANGE}\\ \Omega \end{array}$	RATED POWER P _{70 °C} W	LIMITING ELEMENT VOLTAGE V	TOLERANCE ± %	TEMPERATURE COEFFICIENT ± ppm/°C	
L0603	0603	0.1 to 9.99	0.125	50	1, 2, 3, 5, 10	50, 100, 200, 300	
L0805	0805	0.1 to 9.99	0.2	50	1, 2, 3, 5, 10	50, 100, 200, 300	
L1206	1206	0.1 to 9.99	0.33	50	1, 2, 3, 5, 10	50, 100, 200, 300	
L1505	1505	0.1 to 9.99	0.5	50	1, 2, 3, 5, 10	50, 100, 200, 300	
L2010	2010	0.1 to 9.99	1.0	50	1, 2, 3, 5, 10	50, 100, 200, 300	
L2512	2512	0.1 to 9.99	2.0 (1)	50	1, 2, 3, 5, 10	50, 100, 200, 300	

Note

⁽¹⁾ With special assembly care

CLIMATIC SPECIFICATIONS			
Operating temperature range	-55 °C; +155 °C		

MECHANICAL SPECIFICATIONS				
Substrate	Alumina			
Technology	NiCr + Ta ₂ O ₅			
Coating	Silicone			
Terminations	Solderable B type: SnPb over nickel barrier N type: SnAg over nickel barrier G type: Gold over nickel barrier			

Note

Refer to Application Note "Guidelines for Vishay Sfernice Resistive and Inductive Components" (document number: 52029) for recommended reflow profile. Profile #3 applies

TOLERANCE AND TCR VS. OHMIC VALUE					
$\begin{array}{l} \textbf{OHMIC VALUE} \\ \textbf{RANGE in } \Omega \end{array}$	TIGHTEST TOLERANCE (%) (ppm/°C)		TERMINATIONS		
0R1 < 0R25	1	300	N or B		
0R25 < 0R5	1	200	N or B		
0R5 < 2R5	1	100	N or B		
2R5 < 9R99	1	50	N or B		
0R1 < 0R25	5	300	G		
0R25 < 0R5	5	200	G		
0R < 1R	5	100	G		
1R < 2R5	3	100	G		
2R5 to 9R99	3	50	G		

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GREEN (5-2008)

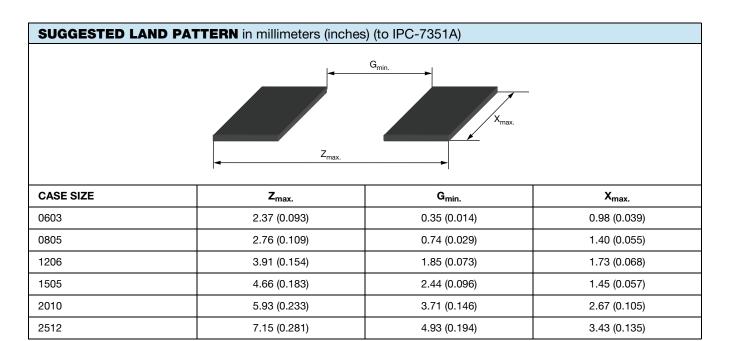


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DIMENSIONS in millimeters (inches)



CASE SIZE	A	В	С	D/E	
	± 0.152 (± 0.006)	± 0.127 (± 0.005)	± 0.127 (+ 0.005)	± 0.127 (± 0.005)	
0603	1.52 (0.060)	0.85 (0.033)		0.38 (0.015)	
0805	1.91 (0.075)	1.27 (0.050)			
1206	3.06 (0.120)	1.60 (0.063)	0.5 (0.020)	0.40 (0.016)	
1505	3.81 (0.150)	1.32 (0.052)	- 0.5 (0.020)	0.48 (0.019)	
2010	5.08 (0.200)	2.54 (0.100)			
2512	6.30 (0.248)	3.30 (0.129)			



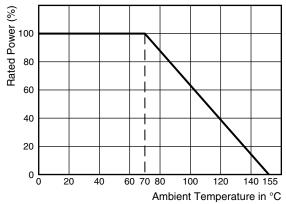
Option: Enlarged Terminations: 0063

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heat sinks (see application note: "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film)": www.vishay.com/doc?53048).

For enlarged terminations: Please consult Vishay Sfernice.

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POWER DERATING CURVE



PACKAGING RULES

Waffle Pack

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover. **To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code**.

PACKAGING

Several types of packaging are proposed: waffle-pack and tape and reel

	MOQ	NUMBER PER P	TAPE		
SIZE		WAFFLE PACK	TAPE A	WIDTH	
		2" × 2"	MIN.	MAX.	
0603		100		5000	8 mm
0805		100			
1206	100	140	100	4000	
1505	100	60	100		
2010		00		2000	12 mm
2512		50		2000	

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided. When several reels are needed for ordered quantity within MOQ and maximum reel capacity: Please consult Vishay Sfernice for specific ordering code.

PERFORMANCE					
		VALUES AND DRIFT			
TESTS	CONDITIONS	MIL-R-55342 REQUIREMENTS	TYPICAL PERFORMANCES		
Thermal shock	MIL-R-55342 C MIL-STD-702, method 107	± 0.25 %	± 0.02 %		
Short time overload	MIL-R-55342 C PARA 3.10.4.7.5	± 0.10 %	± 0.01 %		
Low temperature operation	MIL-R-55342 C PARA 3.9 and 4.7.4	± 0.25 %	± 0.01 %		
Resistance to solder heat	MIL-R-55342 C PARA 3.12, 4.7.7, 4.7.1.2	± 0.25 %	± 0.04 %		
Moisture resistance	MIL-R-55342 C PARA 3.13 and 4.7.8 MIL-STD-202, method 106	± 0.40 %	± 0.01 %		
Moisture resistance	AEC-Q200 85 °C / 85 % RH / 0.1 Pn 1000 h	-	Max. < 0.5 % + 0.05 Ω		
High temperature MIL-R-55342 C PARA 3.11 and 4.7.6		± 0.20 %	± 0.075 %		
MIL-R-55342 C Load life 2000 h Pn at 70 °C MIL-STD-202, method 108		± 0.50 %	± 0.15 %		



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GLOBAL P	GLOBAL PART NUMBER INFORMATION							
L 0 8 0 5 K 1 R 0 0 F B T 0 0 9 9								
GLOBAL MODEL	SIZE	TCR	VALUE	TOLERANCE	TERMINATION	(1) PACKAG	ING OPTION	
L	0603 0805 1206 1505 2010 2512	$H = \pm 50 \text{ ppm}$ $K = \pm 100 \text{ ppm}$ $L = \pm 200 \text{ ppm}$ $M = \pm 300 \text{ ppm}$	R designated decimal point For values under 1R Rxxx	J = ± 5 % K = ± 10 %	B: SnPb over nickel barrier N: SnAg over nickel barrier G: gold over nickel barrier	information Codification Packagi table	n see blank if on of no ing option	
Historical Par	Historical Part Number Example: L 0805 K 1R00 1 % B T R0099							
L	0805	к	1R00	1 %	В	т	R0099	
MODEL	SIZE	TCR	VALUE	TOLERANCE	TERMINATION	PACKAGING	OPTION	

Note

⁽¹⁾ B: lead bearing version N and G: lead (Pb)-free / RoHS version

CODIFICATION OF PACKAGING					
CODE 18	PACKAGING				
WAFFLE PACK					
W	100 min., 1 mult.				
WA	100 min., 100 mult. (available only in size 1206)				
PLASTIC TAPE (Standard for all s	sizes)				
Т	100 min., 1 mult.				
ТА	100 min., 100 mult.				
ТВ	250 min., 250 mult.				
ТС	500 min., 500 mult.				
TD	1000 min., 1000 mult.				
TE	2500 min., 2500 mult.				
TF	Full tape (quantity depending on size of chips)				
PAPER TAPE (Available for 0603,	0805, and 1206. Please consult Vishay Sfernice for other sizes)				
PT	100 min., 1 mult.				
PA	100 min., 100 mult.				
PB	250 min., 250 mult.				
PC	500 min., 500 mult.				
PD	1000 min., 1000 mult.				
PE	2500 min., 2500 mult.				
PF	Full tape (quantity depending on size of chips)				



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